Smart Damper Block Diagram
Battery Jumper/Protection

Motor: DRV8833

Buck Converter: TPS62745

Temperature/Humidity Sensor 1

Temperature/Humidity Sensor 2

Pressure/Temp Sensor

DC Motor Jumpsers

Motor Driver Logic Table

Rotary Position Sensor

Battery Jumper/Protection

Motor: DRV8833

Buck Converter: TPS62745

Temperature/Humidity Sensor 1

Temperature/Humidity Sensor 2

Pressure/Temp Sensor

DC Motor Jumpsers

Motor Driver Logic Table

Rotary Position Sensor
BLE/MCU: CC2650

LPRF Bypass Capacitors & DC-DC Passives

Reset Switch and User Buttons

JTAG Programming Interface

I2C Pullup Resistors

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**Variant/Label Table**

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
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<tr>
<td>001</td>
<td>Smart-Lock</td>
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**Assembly Notes**

- **ZZ1**
  - Note attached only to PCB labels only

- **ZZ2**
  - ESD sensitive. ESD precautions shall be observed.

- **ZZ3**
  - Must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

- **ZZ4**
  - These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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